Material Composition Specification

GPR-1A Case

Device average mass . . . . . 342 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.34%	1.16	Si	7440-21-3	0.34%	1.16	3,392
axial lead	wire	80.7%	276	Cu	7440-50-8	80.65%	275.83	806,520
				Zn	7440-66-6	0.05%	0.17	497
	moly slug	13.39%	45.8	Mo	7439-98-7	13.39%	45.8	133,918
die attach	solder	0.5%	1.71	Cu	7440-50-8	0.4%	1.36	3,977
				Ag	7440-22-4	0.08%	0.26	760
				P	7723-14-0	0.03%	0.09	263
encapsulation	glass	2.92%	10	Zn	7440-66-6	1.4%	4.8	14,049
				O	7782-44-7	1.07%	3.67	10,741
				B	7440-42-8	0.28%	0.95	2,780
				Si	7440-21-3	0.11%	0.38	1,112
				Pb	7439-92-1	0.06%	0.2	585
plating*	tin/lead process	2.05%	7.0	Sn	7440-31-5	1.74%	5.96	17,427
				Pb	7439-92-1	0.3%	1.04	3,041
	matte tin	2.05%	7.0	Sn	7440-31-5	2.05%	7.0	20,468

*For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.